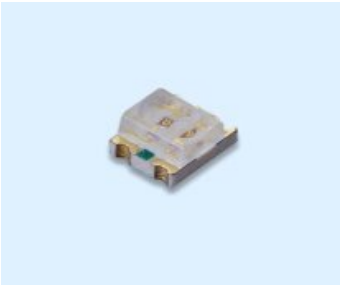
EVERLIGHT ELECTRONICS CO.,LTD.

Technical Data Sheet

Chip LED with Bi-Color(Multi-Color)

11-22/Y2G6C-A01/2T



Features

- Package in 8mm tape on 7″ diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Multi-color type.
- Pb-Free.
- The product itself will remain within RoHS compliant version.

Descriptions

- The 11-22 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

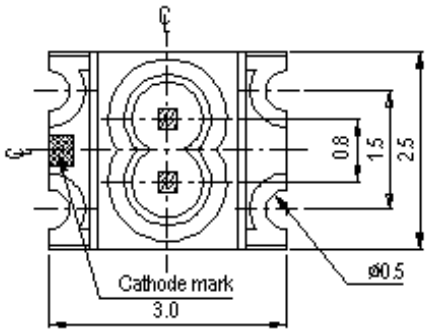
Applications

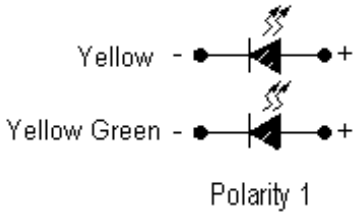
- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

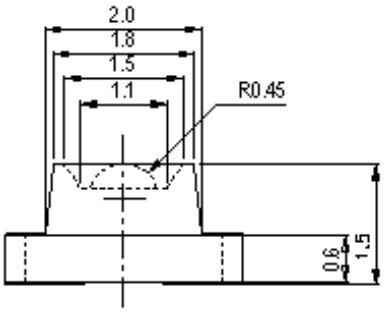
Device Selection Guide

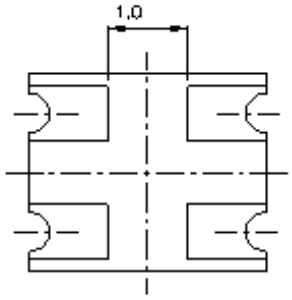
Chip		Emitted Color	Resin Color
Type	Material		
Y2	AlGaInP	Brilliant Yellow	Water Clear
G6	AlGaInP	Brilliant Yellow Green	

Package Outline Dimensions

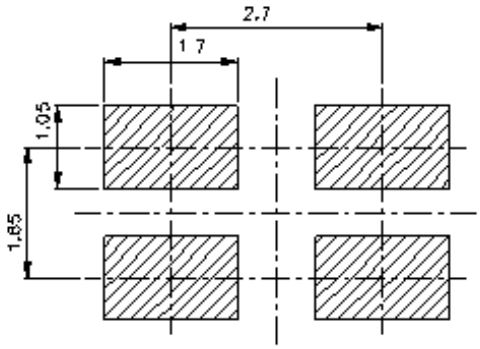








For reflow soldering (propose)



Notes: Tolerances Unless Dimension ±0.1mm, Unit = mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	Y2:25 G6:25	mA
Power Dissipation	Pd	Y2:60 G6:60	mW
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	Y2:60 G6:60	mA
Electrostatic Discharge(HBM)	ESD	Y2:2000 G6:2000	V
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40~ +90	℃
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol		Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	Y2 G6	112 57	225 140	450 225	mcd	I_F=20mA
Viewing Angle	2θ1/2		-----	60	-----	deg	
Peak Wavelength	λp	Y2 G6	-----	591 518	-----	nm	
Dominant Wavelength	λd	Y2 G6	585 567	---- ----	595 573	nm	
Spectrum Radiation Bandwidth	△λ	Y2 G6	-----	15 20	-----	nm	
Forward Voltage	V_F	Y2 G6	1.7 1.7	2.0 2.0	2.4 2.4	V	
Reverse Current	I_R	Y2 G6	-----	-----	10 10	μA	V_R=5V

Notes:

1.Tolerance of Luminous Intensity ±11%

2.Tolerance of Dominant Wavelength ±1nm

Bin Range Of Luminous Intensity

Y2

Bin	Min	Max	Unit	Condition
R	112	180	mcd	I_F =20mA
S	180	285		
T	285	450		

G6

Bin	Min	Max	Unit	Condition
1	57	90	mcd	I_F =20mA
2	90	140		
3	140	225		

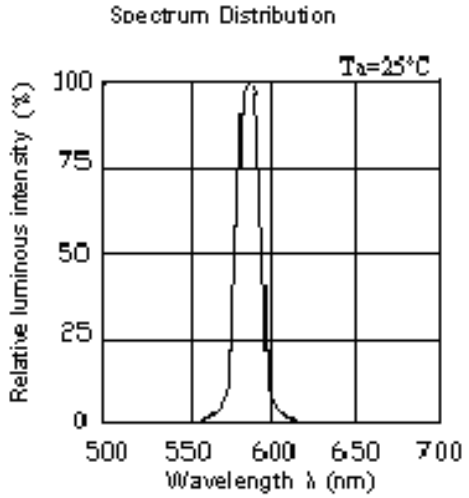
Notes:

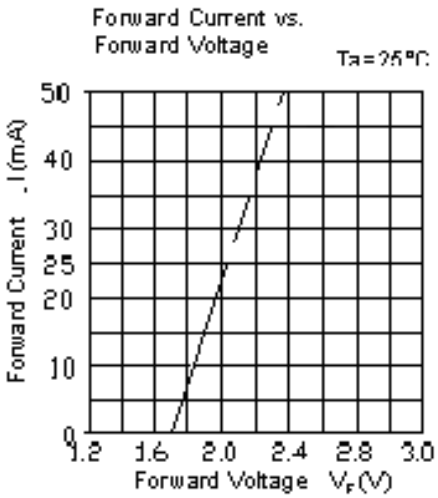
1.Tolerance of Luminous Intensity ±11%

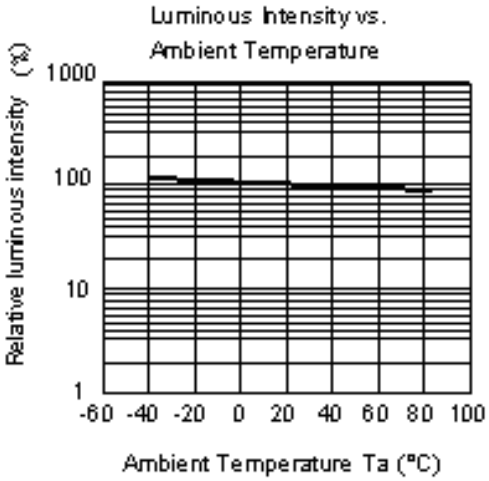
2.Tolerance of Dominant Wavelength ±1nm

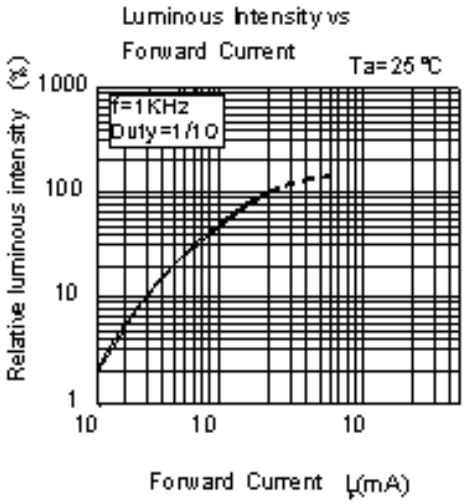
Typical Electro-Optical Characteristics Curves

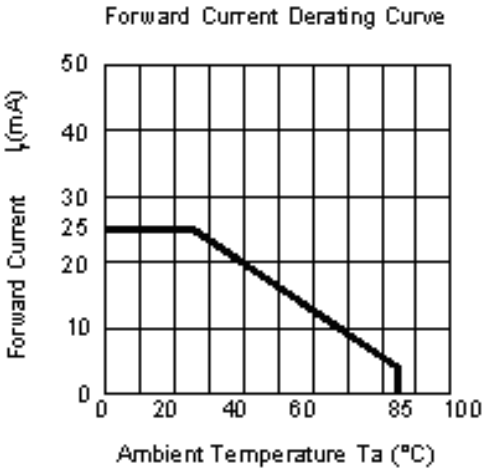
Y2

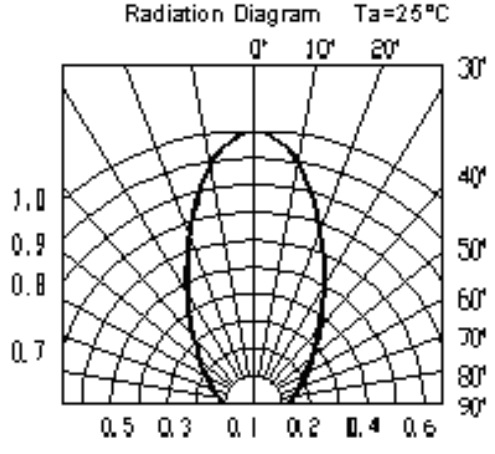








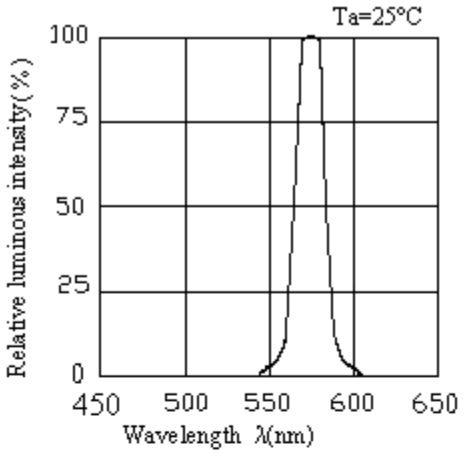




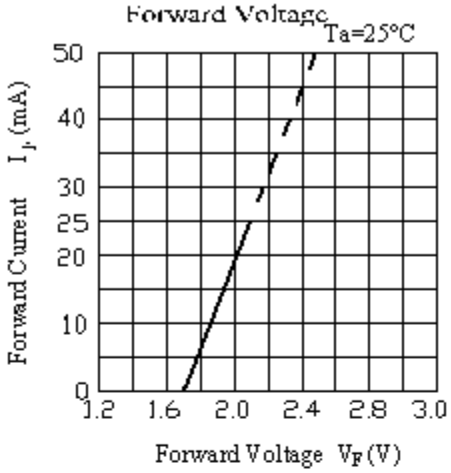
Typical Electro-Optical Characteristics Curves

G6

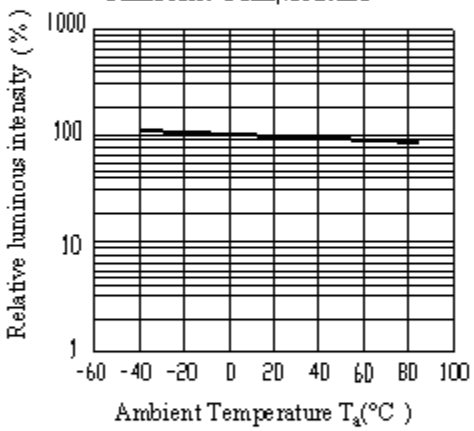
Spectrum Distribution



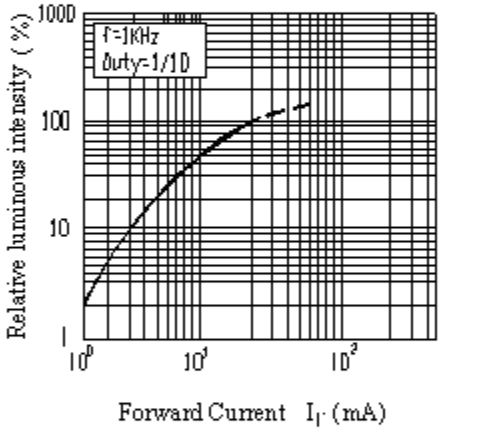
Forward Current vs. Forward Voltage



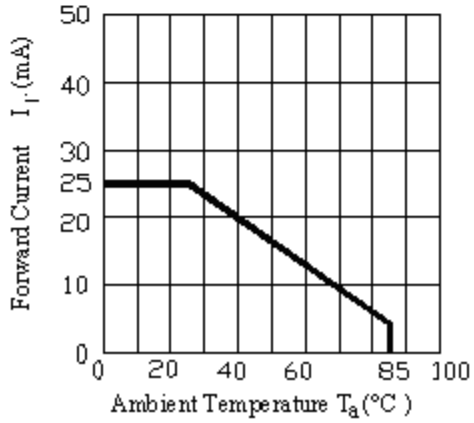
Luminous Intensity vs. Ambient Temperature



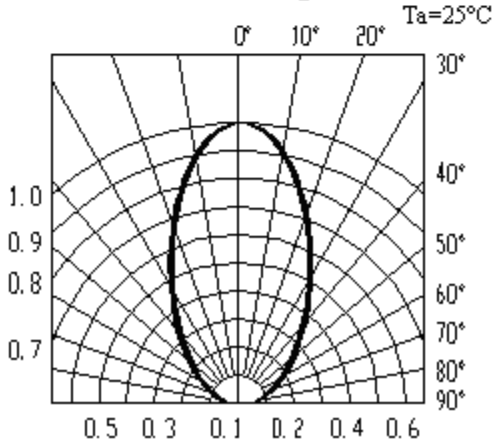
Luminous Intensity vs Forward Current



Forward Current Derating Curve



Radiation Diagram



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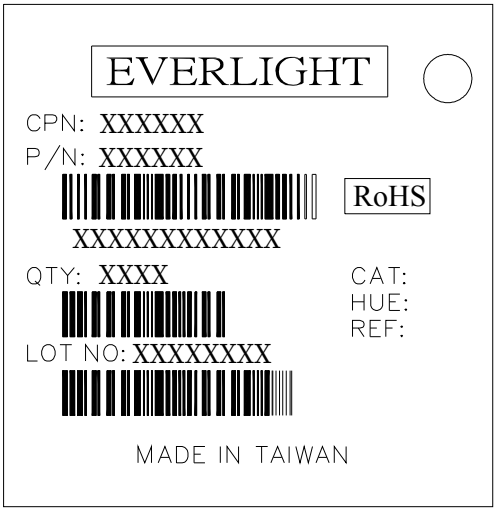
Label explanation

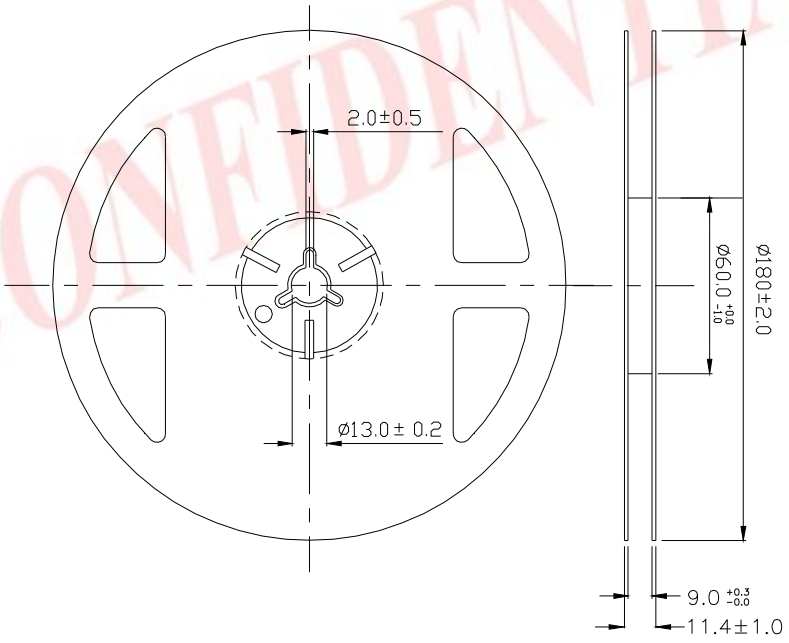
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

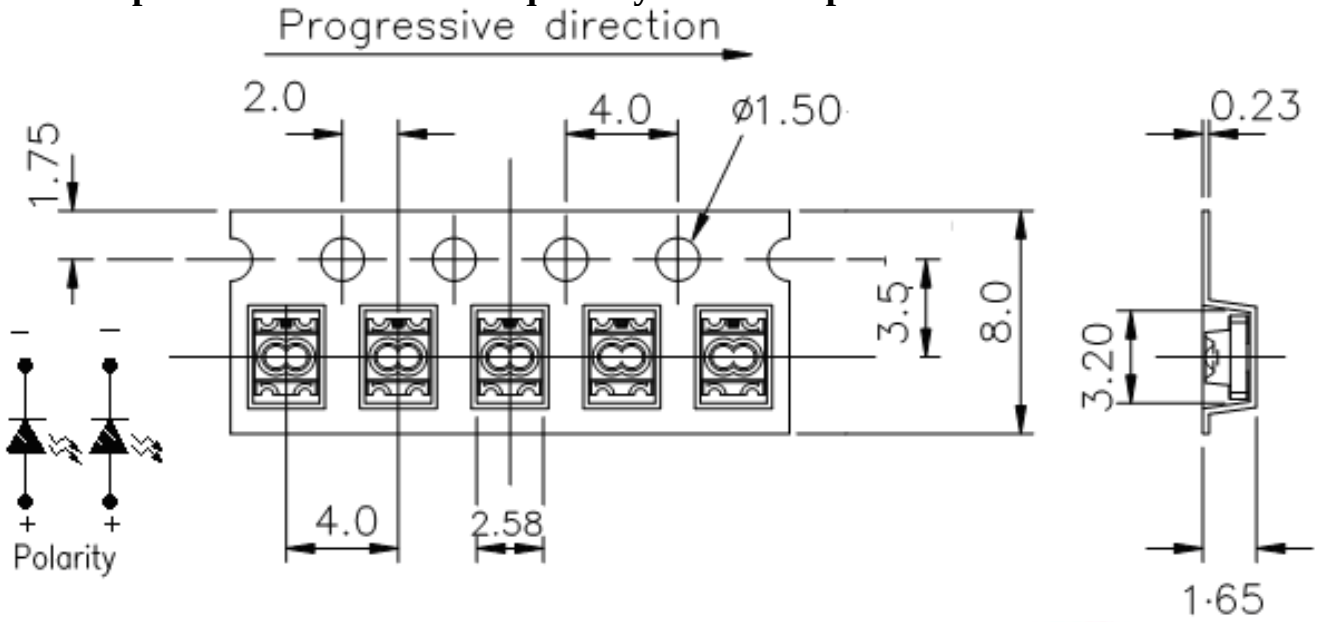


Reel Dimensions



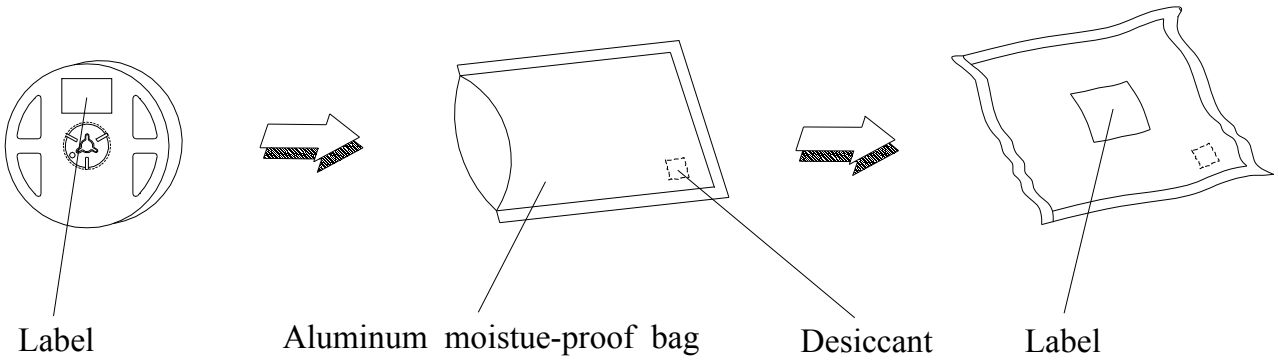
Note: Tolerances Unless Dimension ±0.1mm,Unit = mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: Tolerances Unless Dimension ±0.1mm , Unit = mm

Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level：90%
LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

   Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

   2.1 Do not open moisture proof bag before the products are ready to use.

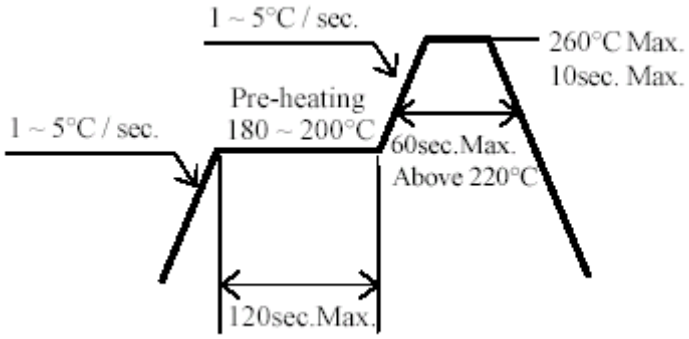
   2.2 Before opening the package: The LEDs should be kept at 30 ℃ or less and 90%RH or less.

   2.3 After opening the package: The LED's floor life is 1 year under 30 ℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

   2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
   Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

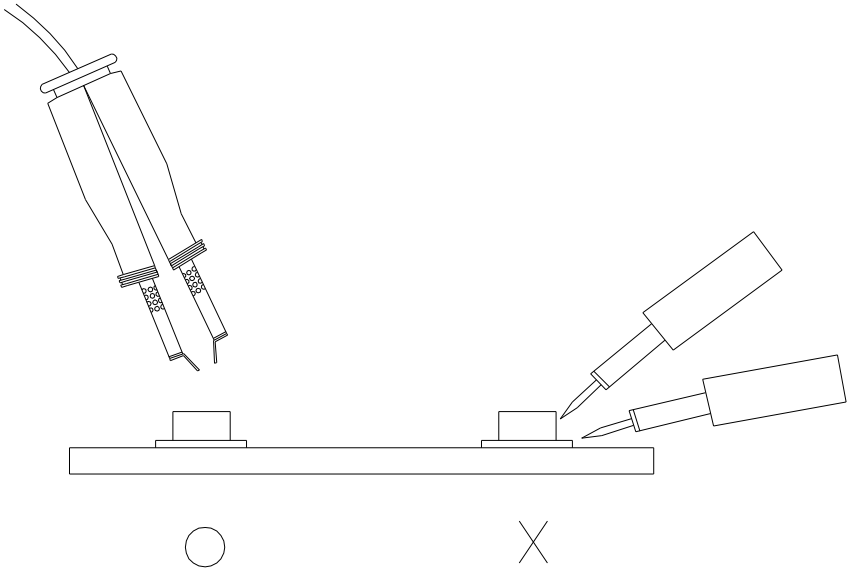
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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